



Soldering Flux LF 50 SMT

- **MBO LF 50 SMT** is specifically manufactured to leave no remaining residue after soldering to eliminate the need for circuit cleaning and effectively saving the relative costs in lead free wave soldering.
- Dirt accumulation in machines and on circuit boards carriages is drastically reduced.
- Soldering efficiency is equal to resinous flux, type RMA.
- Halide free, it leaves no corrosive elements after processing.
- **MBO LF 50 SMT** flux is manufactured to conform with French Standards NFC 90550, German DIN 8511 and **British Standard B.S.5625**
- **MBO LF 50 SMT** flux meets new RoHS requirements,

Physiochemical Characteristics:

Solution	: Alcoholised
Colour	: Colourless
Density at 20°C	: 0.815 +/- 0.005
Non volatile content	: < 4 %
Chlorine rate	: Halide free
Flash point	: 18°C
Acidity	: 27 +/- 5 mg/ml
Corrosiveness	: None
Insulation resistance	: > 100 GΩ

Application Notes:

Flux MBO LF 50 SMT can be used with all fluxing systems – spray, foam, and dipping in all types of automatic machines (single or double wave).

Carry out a regular check of the density or acidity index and maintain the level by adding **DILUANT D40S**. Nominal density is 0.810 to 0.820 @ 20°C.

The circuit topside drying temperature after fluxing should be 90 to 130°C.

The alloy bath temperature should be between 235 and 250°C for leaded alloys and 255 to 270°C for lead free alloys.

Conveyor speed should be between 0.8 and 2 meters per minute, depend on the type of circuit. Contact time between circuit and solder wave should not exceed 3 to 4 seconds.

Health and Safety:

As with all soldering fluxes, MBO 45 must be used in a well ventilated area away from any source of flame or ignition (COSH sheet available).

Packaging:

Throwaway 10 plastic containers of 5, 10 and 20 litres.

Store in original hermetically sealed containers, stored at an ideal temperature near 20°C for 12 months maximum.